

SAN DIEGO, CA – March 5, 2025 – Chiplet Summit Reports Rapid Growth in Successful Third Year

Chiplet Summit held its third annual event at the Santa Clara Convention Center on January 21-23. Both registration and total attendance nearly doubled from 2024 (1765 and 1047, respectively). Key areas of interest were advanced packaging methods, high-speed die-to-die interfaces, generative AI applications, and the open chiplet economy. Keynoters were Synopsys, Alphawave Semi, Arm, Teradyne, Cadence, Keysight Technologies and the Open Compute Project.

The conference featured panels on design challenges, breakthroughs, packaging, making money with chiplets, and near-term trends. Pre-conference tutorials covered interfaces, packaging, and the open chiplet economy. A superpanel, moderated by Electronic Design editor-in-chief Bill Wong, focused on solving the AI Energy Gap. Leading exhibitors and sponsors, in addition to our keynoters, included Applied Materials, Achronix/PRIMEMAS, Deca Technologies, and NHanced Systems. Slides from the sessions and keynotes are available on the website at no charge.

“The rapid increase in CS25 participation and attendance reflects the growing recognition that chiplet architectures are the best way to utilize the highest density processes,” reported Chuck Sobey, Summit General Chair. He noted that “Chiplets are the standard way to implement leading-edge chips for industry giants such as AMD, Intel, and Samsung. Attendees valued the opportunity to meet and talk with specialists in all stages: partitioning, design, packaging, integration, test, and manufacturing.”

Supporting Resources -

- Visit Chiplet Summit: ChipletSummit.com
- Follow Chiplet Summit on linkedin.com/company/chiplet-summit
- Follow Chiplet Summit on Facebook.com/ChipletSummit

To discuss sponsoring and exhibiting next year, contact:

Elizabeth Leventhal, Exhibit Sales Director
Elizabeth@ChipletSummit.com
+1.760.809.5755

To ask about next year's program, contact:

Lance Leventhal, Program Chairperson
Lance@ChipletSummit.com
+1.858.756.3327

About Chippet Summit

Chippet Summit is a technical conference and trade show that showcases the emerging chippet market. The Summit is a product of Semper Technologies. For more information, see www.chippetsummit.com.

Media Contact:

Elizabeth Leventhal

+1.760.809.5755

Press@ChippetSummit.com